

Features

- 175°C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Terminals finish: Tin Lead-free plated
- This is a Pb Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- · Reverse battery protection

Maximum Ratings(limiting values, T_C =25°C unless otherwise specified)

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$egin{array}{c} V_{RRM} \ V_{RWM} \ V_{R} \end{array}$	-	150	٧
Average Rectified Forward Current	I _{F (AV)}	Tc=90°C, In DC	30(Per Leg) 60(Per Device)	Α
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I _{FSM}	8.3ms, Half Sine pulse	270	Α

Electrical Characteristics:

Characteristics	Symbol	Condition	Тур.	Max.	Units
Forward Voltage Drop(Per Leg)*	V _{F1}	@ 30A, Pulse, T _J = 25 °C		0.94	V
	V _{F2}	@ 30A, Pulse, T _J = 125 °C	0.79	0.85	V
Reverse Current(Per Leg)*	I _{R1}	@V _R = rated V _{R,} T _J = 25 °C	0.0005	1.00	mA
	I _{R2}	@V _R = rated V _R , T _J = 125 °C	0.07	10	mA
Junction Capacitance(Per Leg)	Ст	$@V_R = 5V, T_C = 25 ^{\circ}C, f_{SIG} = 1MHz$	490	800	pF
Voltage Rate of Change	dv/dt	-	-	10,000	V/μs
RSM Isolation Voltage (t = 1.0 second, R. H. < =30%, T _A = 25 °C)	V _{ISO}	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.		4500	V
,		Clip mounting, the epoxy body is inside the heatsink.	-	3500	
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

^{*} Pulse width < 300 µs, duty cycle < 2%

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Thermal-Mechanical Specifications:

Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	TJ	-	-55 to +175	°C
Storage Temperature	T _{stg}	-	-55 to +175	°C
Typical Thermal Resistance Junction to Case(Per Leg)	R ₀ JC	DC operation	3.5	°C/W
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

Ratings and Characteristics Curves

Figure1 Typical Forward Characteristics

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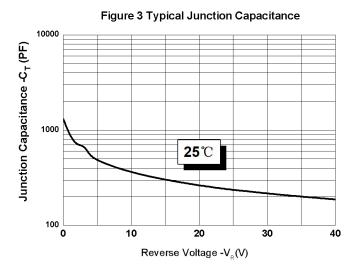
125°C

25°C

100

25°C

Forward Voltage -V_E(V)



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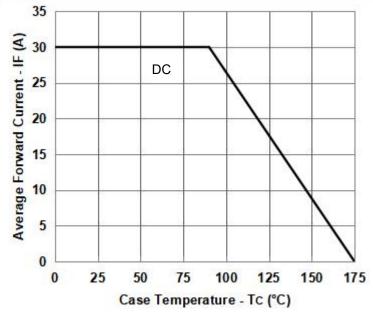
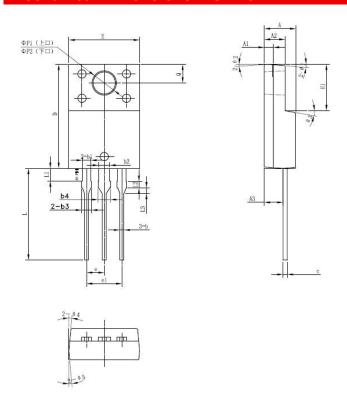


Fig.4 Forward Current Derating Curve

Mechanical Dimensions ITO-220AB



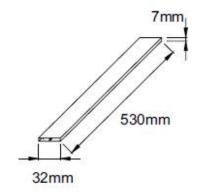
CVMDOL	Millimeters				
SYMBOL	MIN.	TYP.	MAX.		
Α	4.30	4.50	4.70		
A1	1.10	1.30	1.50		
A2	2.80	3.00	3.20		
A3	2.50	2.70	2.90		
b	0.50	0.60	0.75		
b1	1.10	1.20	1.35		
b2	1.50	1.60	1.75		
b3	1.20	1.30	1.45		
b4	1.60	1.70	1.85		
С	0.50	0.60	0.75		
D	14.80	15.00	15.20		
<u> </u>	9.96	10.16	10.36		
е		2.55			
e1		5.10			
H1	6.50	6.70	6.90		
L	12.70	13.20	13.70		
<u>L1</u>	1.60	1.80	2.00		
L2	0.80	1.00	1.20		
L3	0.60	0.80	1.00		
Φ P1(├ □)	3.30	3.50	3.70		
ΦP2 (下口)	2.99	3.19	3.39		
Q	2.50	2.70	2.90		
Θ1		5°			
Θ2		4°			
Θ3		10°			
Θ4		5°			
Θ5		5°			

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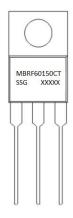




Tube Specification



Marking Diagram



Where XXXXX is YYWWL

MBR = Device Type = Package type 60 = Forward Current (60A) = Reverse Voltage (150V) 150 CT = Configuration SSG = SSG= Year ww = Week = Lot Number Cautions: Molding resin

Epoxy resin UL:94V-0

Ordering Information

Device	Package	Shipping
MBRF60150CT	ITO-220AB (Pb-Free)	50 pcs/ tube

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